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1. Name of conveying party(ies):
 Kyoung Ro YOON Yoon Su KIM
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2. Name and Address of receiving party(ies):
 SAMSUNG ELECTRO-MECHANICS CO., LTD.
 314 Maetan 3-dong, Yeongtong-gu,
 Suwon-si, Gyeonggi-do 443-743,
 Republic of Korea

3. Nature of conveyance:
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 Execution Date(s): June 23, 2006

4. Application number(s) or patent number(s):
 This document is being filed together with a new application.

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5. Name and address of party to whom correspondence concerning document should be mailed:
 STAAS & HALSEY LLP Our Docket: 1954.1003
 Attention: David M. Pitcher
 1201 New York Ave., N.W., Suite 700
 Washington, D.C. 20005

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41)..... (\$ 40.00 per Patent or Application in Assignment)
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IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter, "ASSIGNOR") by

SAMSUNG ELECTRO-MECHANICS CO., LTD.

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(hereinafter, "ASSIGNEE"), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled

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relating to International Patent Application PCT/_____/_____ and/or for which application for Letters Patent of the United States was executed on even date herewith or, if not so executed, was:

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IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).

(Typed Name & Signature of Inventor(s))

(Date)

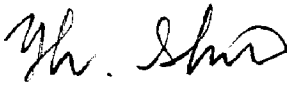
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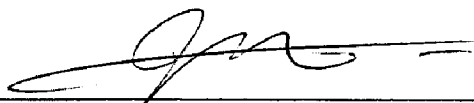
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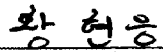
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